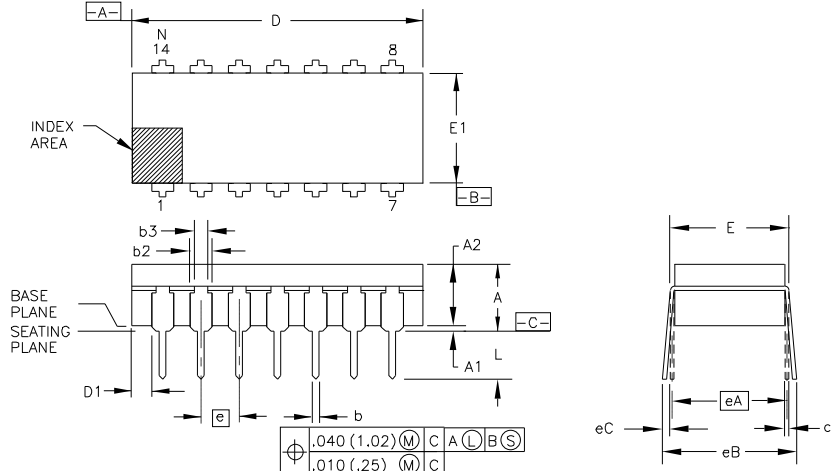


Package Number 163 - 14-Lead CERDIP, .300 Wide



⊕	.040 (1.02)	(M)	C	A	(L)	B	(S)
	.010 (.25)	(M)	C				

DIM	INCHES		MILLIMETERS		N	E	DIM	INCHES		MILLIMETERS		N	E
	MIN.	MAX.	MIN.	MAX.				MIN.	MAX.	MIN.	MAX.		
A	--	.230	--	5.84			eC	.000	--	0.00	--	5	
A1	.015	--	0.38	--			L	.100	--	2.54	--		
A2	.140	.180	3.56	4.57			N		14		14		6
b	.015	.023	0.38	0.58	9								
b2	.045	.070	1.14	1.78									
b3	.035	TYP	0.89	TYP									
c	.008	.015	0.20	0.38	9								
D	.753	.767	19.13	19.48	3								
D1	.005	--	0.13	--									
E	.300	.325	7.62	8.26	4								
E1	.280	.295	7.11	7.50	3								
e	.100	BASIC	2.54	BASIC									
eA	.300	BASIC	7.62	BASIC	4								
eB	--	.450	--	11.43	5								

- NOTES:
1. CONTROLLING DIMENSIONS: INCH.
  2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
  3. D AND E1 DIMENSIONS INCLUDE ALLOWANCE FOR GLASS OVERRUN AND MENISCUS, AND LID TO BASE MISMATCH.
  4. E AND eA MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO PLANE C.
  5. eB AND eC ARE MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED. eC MUST BE ZERO OR GREATER.
  6. N IS THE MAXIMUM NUMBER OF TERMINAL POSITIONS.

7. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION.
8. FOR AUTOMATIC INSERTION, ANY RAISED IRREGULARITY ON THE TOP SURFACE (STEP, MESA, ETC.) SHALL BE SYMMETRICAL ABOUT THE LATERAL AND LONGITUDINAL PACKAGE CENTERLINES.
9. b AND c DIMENSIONS INCLUDE BOTH THE BASE MATERIAL AND THE COATING OR PLATING ON THE LEADS.
10. A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.

PACKAGE NUMBER: ZZ163 | REV.: C  
JEDEC NUMBER: NONE



PACKAGE DRAWING

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